

2011 CASPA/SEMI High Tech Job Fair



Shanghai Hua Hong NEC Electronics Company, Limited

Job Opening

Position: High voltage discrete device program manager to cover SJNFET and IGBT

Qualifications:

1. master degree or above;
2. 7 to 10 years' working experience in semiconductor process integration development;
3. 5 years plus power device especially Super Junction, IGBT and FRD device development experience;
4. experience with IGBT and FRD device process module, process integration and device design;
5. expertise in power device physics, DC/AC characterization, failure mechanism and characterization;
6. leadership and team building capability;

Position: RF engineering and program manager

Qualifications:

1. master degree or above;
2. 7 to 10 years' working experience in semiconductor process integration development;
3. 7 years plus SiGe/HBT device development experience in RF field;
4. experienced with high speed, high voltage SiGe/HBT process and RF power device design and process integration;
5. expertise in SiGe/HBT, inductor and capacitor measurement, RF modeling, PDK, library and IP development;
6. ability to coordinate third party vendor to accomplish item 5 if necessary;
7. leadership and team building capability

Position: Oversea Sales

Qualifications:

1. BS/MS in Physics, Electrical Engineering or Microelectronics, MBA is a plus;
2. 5+ years of foundry Fab operation experience, prefer in integration, and at least 2 years of Foundry sales experience are preferred;
3. familiar with the basic foundry sales flow, good basic knowledge of semiconductor devices such as MOSFET, embedded NVM will be helpful;
4. self motivated, good team work and communication skills required;
5. native Chinese language and fluent English are mandatory, 3rd language in Japanese / Korean or any European is plus;

Website: www.hhnec.com

Apply to: hr@hhnec.com